

Appl. No. 10/717,731  
Response dated Aug, 16, 2006  
Reply to Office action dated May 16, 2006

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of claims:**

1-16. (canceled)

17. (currently amended) The semiconductor device of claim ~~[[16]]~~ 18, wherein the chip carrier is selected from a group consisting of a substrate and a leadframe.

18. (currently amended) ~~The semiconductor device of claim 16, wherein the component with negative CTE is~~ A semiconductor device comprising:

a semiconductor die;

a chip carrier;

a die attach material including a component of a tungstate material; and

the semiconductor die attached to the chip carrier with the die attach material,

which covers an entire die surface.

19. (currently amended) The semiconductor device of claim ~~[[16]]~~ 18, further comprising an encapsulant that encapsulates the semiconductor die, the encapsulant including a component of negative-CTE.

20. (previously presented) The semiconductor device of claim 19, wherein the encapsulant includes a tungstate material.

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21. (previously presented) The semiconductor device of claim 19, wherein the encapsulant is selected from a group consisting of a mold compound and a glob-top material.

25. (previously presented) The semiconductor of claim 19, in which the die attaching material and the encapsulant include a component selected from a group consisting of zirconium tungstate, hafnium tungstate, and a solution of zirconium and hafnium tungstate.

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